

Gaseous Tracking (TPC) Summary

LCWT09
Nov. 5, 2009
LAL, Orsay

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DESY/FLC

Wednesday 04 November 2009

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08:45->10:15 Plans of Subdetectors - Gaseous Tracking
(Convener: Yulan Li (*Tsinghua University*) , Matsuda Takeshi (*IPNS/KEK*))

- 08:45 TPC large prototype beam test and the future (40') Klaus Dehmelt (*DESY FLC*)
- 09:25 Test beam and test beam facility for TPC R&D (20') Ron Settles (*Max-Planck-Institut für Physik*)
- 09:45 Discussion (30')

R&D Phases

1. Demonstration Phase: Small prototype tests still going!

Provide a basic evaluation of the properties of an MPGD TPC and demonstrate that the requirement (1-b,c) can be met using small prototypes.

1. Consolidation Phase: LP1: 2007-2010 & LP2 2010 –

Design, build and operate a “Large Prototype” (of large number of measured points) at the EUDET facility in DESY comparing technologies and demonstrating (1-a) in a way.

1. Design Phase:

Start working on an engineering design for aspects of the TPC at ILC.

(LC TPC collaboration: MOU)

At each phase, we perform beam tests
probably with different purposes.

Options of MPGD for ILC TPC

Based on the studies with small MPGD TPC Prototypes

Analog TPC: Immediate options if the current ILC schedule

(1) Multi layer GEM + Narrow (1mm wide) pad readout:

Defocusing by multilayer GEM

Narrow (1mm) pads → Larger readout channels

Effective No. of electrons (N_{eff}):

(2) MicroMEGAS + Resistive anode pad (2-3mm wide)

Widening signal by resistive anode

Wider pads → Less readout channels

N_{eff} :

Digital TPC:

(3) Ingrid-MicroMEGAS + Timepix: Digital TPC

Digital → Free from the gas gain fluctuation

More information from primary electrons and

Thus better position resolution (to be demonstrated)

(4) Multilayer GEM + Timepix: More an analog TPC?

Need to improve the efficiency for primary electrons

TPC Large Prototype Beam Test (LP1)



LP1 at DESY T24-1 beam area

TPC Large Prototype Tests: LP1

2008:

Nov-Dec **MicroMEGAS modles w/ resistive anode (T2K electronics)**

2009:

Feb-Apr **3 Asian GEM Modules w/o Gating GEM (3,000ch ALTRO electronics)**

Apr **TDC electronics with an Asian GEM Module**

Apr-May **Maintenance of PCMAG**

May-Jun **Micromegas w/ two different resistive anodes (New T2K electronics)**

Setup and test of laser–cathode calibration

Jun **GEM+Timepix (Bonn)**

Jun **Installation of PCMAG lifting stage and Si support structure**

July **TDC electronics with an Asian GEM module**

ALTRO electronics study w/ an Asian GEM module

July-Aug **Installation of PCMAG lifting stage**

Aug **MicroMegas w/o resistive anode with laser-cathode calibration**

Sept **A Bonn GEM module (A small aria GEM with ALTRO electronics)**

2010: (see next page)

Please see for current LP results Klaus Dehmelt talk.

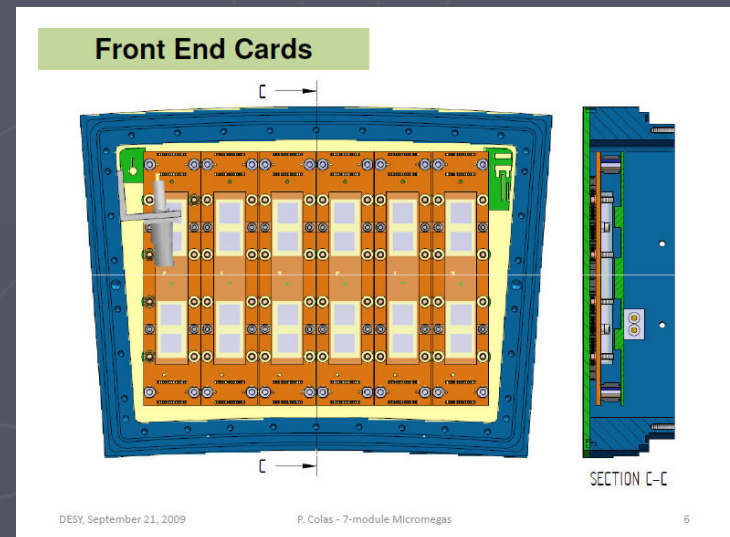
TPC Large Prototype Beam Test: LP1 in 2010

“Demonstrate full-volume trucking in non-uniform magnetic field, trying to provide a proof for the momentum resolution at LC TPC”

2010:

Spring 4 Asian GEM Modules w/ gating GEM (10,000ch ALTRO electronics)
DESY GEM modules (w/ wire gating) (10,000ch ALTRO electronics)
Fall 7 MicroMEGAS modules w/ resistive anode (12,000ch T2K electronics)

New MicroMEGAS modules in 2010



TPC Large Prototype Beam Test (LP2) from 2011

2011 Move to a **high momentum hadron beam**
high momentum: 10 - 100 GeV/c

- ← Limitation using electron beam to measure momentum
- Discussion to be made in LC TPC collaboration
based on the information at LCWT09

Most probable option: Move the current TPC large prototype with PCMAG.

Also Possible beam tests with the TPC small prototypes for the ion issue and gating, the double track separation, etc.

Location and the question if the bunch structure.

Two Other Important R&D Issues in 2010-2012

Advanced endplate:

Requirement: **thickness 15% X_0**

Thin endplate

High density, low power electronics to match small pads
(1 x 4mm) surface-mounted directly on the back of
pad plane of MPGD detector module

Power delivery, power pulsing and cooling

LP2 beam tests with Advanced endplate (budget)

Ion Feed back and Ion disks:

Ion feed back ration and beam backgrounds

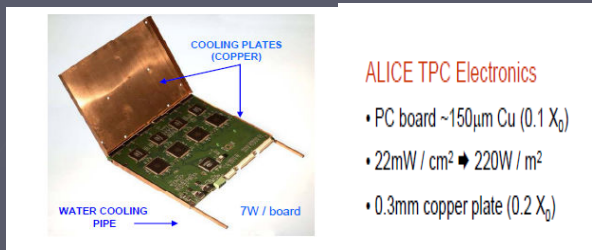
Estimate distortion due to the ion disks (simulation)

Options of gating device: Wire gating, GEM gating

Methods of calibration

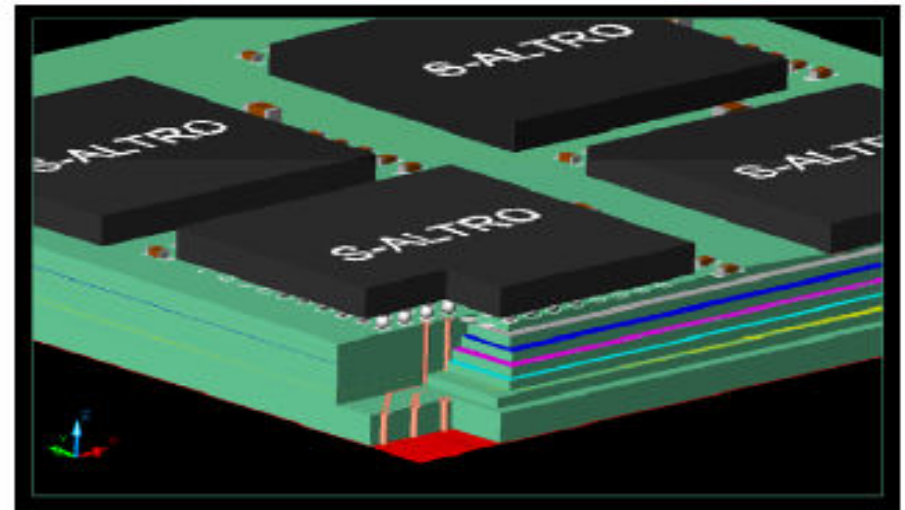
Advanced Endplate: S-ALTRO

High density, low power, low material electronics for TPC



Musa / CERN

ALICE TPC



The S-ALTRO team at CERN

P. Aspell, H. Franca Santos, E. Garcia,
A. Junique, M. Mager, C. Patauner,
A. Ur Rehman, L. Musa

ILC (ILD) TPC

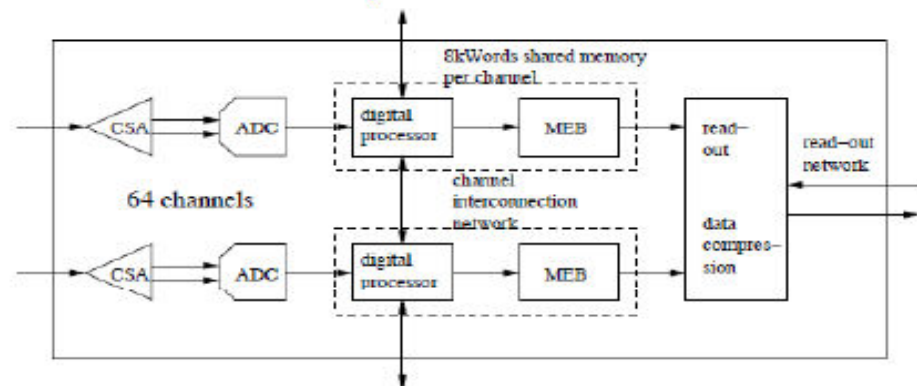
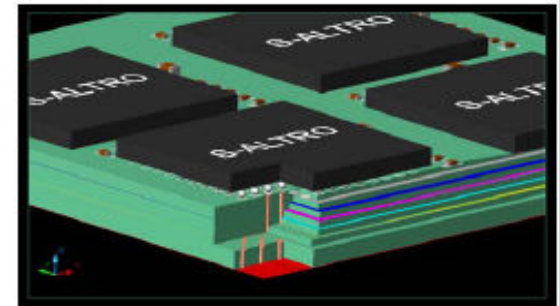
Advanced Endplate: S-ALTRO

High density, low power electronics for TPC

A multi purpose readout chip for TPC detectors

A multi-purpose readout chip for TPC detectors

- 64 complete readout channels (from detector pad to data link)
- programmable charge sensitive amplifier
 - sensitivity to a charge in the range $\sim 10^2 - \sim 10^6$
 - programmable shaping time in the range 30 to 300ns
- 10-bit 40 MSPS ADCs
- 8k multi acquisition memory per channel (dynamically allocated)
- digital signal conditioning (4th order IIR filter and FIR filter) for baseline correction
- 3-D zero suppression
- lossless data compression
- readout net work controller
- output bandwidth 160 Mbyte/sec



Advanced Endplate: S-ALTRO

Chip size and Power consumption

L. Musa

Chip size: (*estimate)

Shaping amplifier	0.2 mm ²
ADC	0.7 mm ² (*)
Digital processor	0.6 mm ² (*)
When 1.5mm ² /channel	
64 ch/chip	→ ~ 100 mm²

PCB board ~ 27 x 27 cm²
 ⇒ ~16400 pads or 256 chips/board

Bare die flip-chip mounted or chip scale package

Minimum-size capacitors (0.6x0.3x0.3mm³)

Standard linear voltage regulators

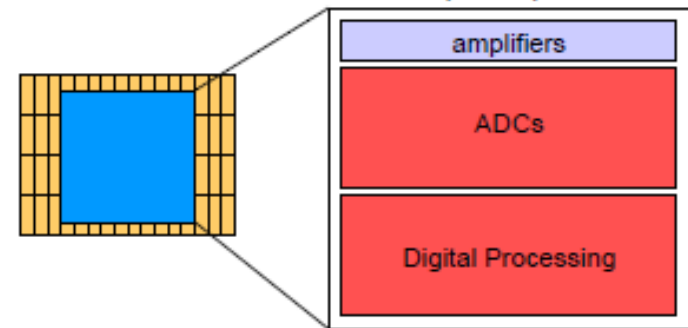
Data link based on ALICE SPD GOL MCM

Power consumption: (*) 10 -40MHz

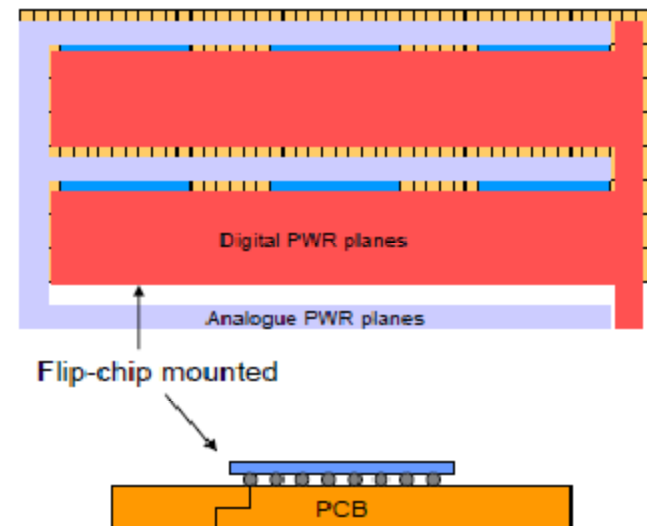
Amplifier	8 mW/channel
ADC	12-34 mW/channel (*)
Digital Proc	4 mW/channel
Power reg.	2 mW/channel
Data links	2 mW/channel
Power reg. eff.	75%
Total	32-60mW/channel (*)
Duty cycle:	1.5% (Electrical duty)
Average power	0.5 mW / channel
	100 -200W/m² (*)

pad: 1 x 4mm²

Chip floorplan



PCB topology and layer stack-up



Advanced Endplate: S-ALTRO

Status and Schedule

Status & Plans

Status

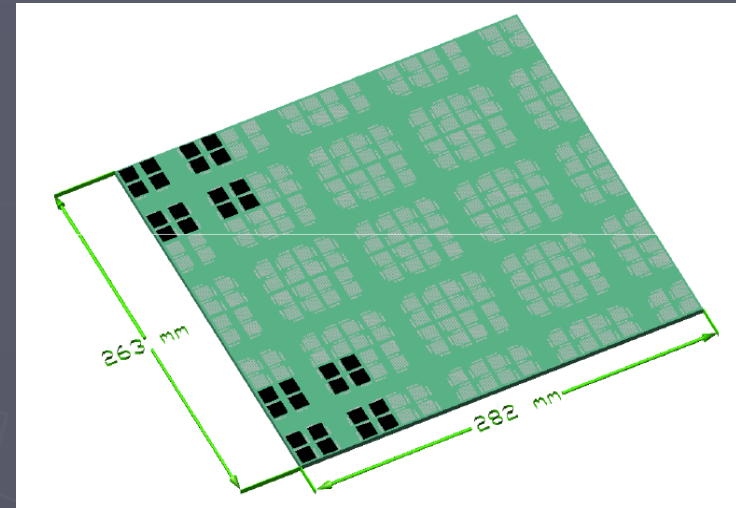
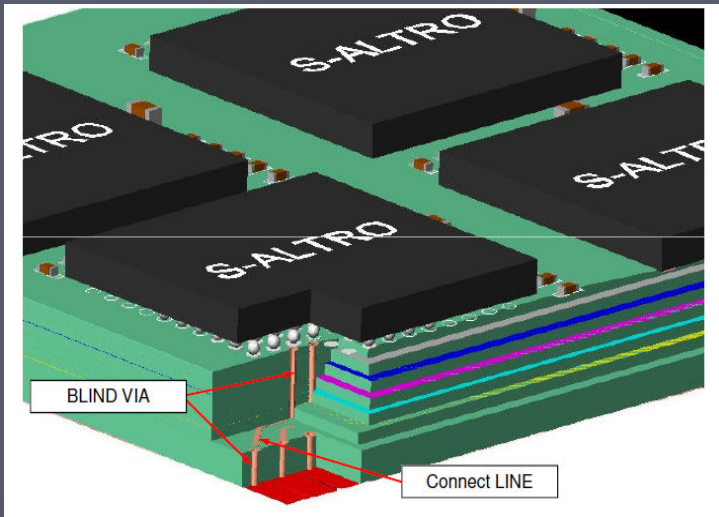
- 2006 12-channel prototype of CSA (no programmability)
- 2007 16-channel prototype programmable (1000 chips for LPTPC @ Desy)
- 2009 2-channel ADC prototype (samples expected in June)
- 08/09 specifications digital blocks and design entry (Verilog) of data processor
- 2009 first design of readout board

Plans

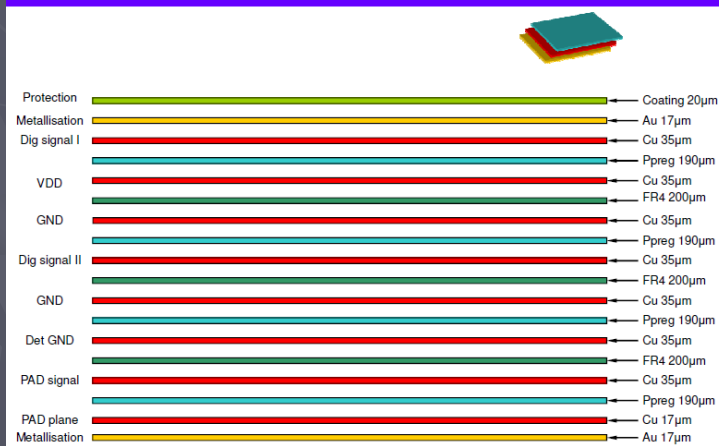
- 2009
 - characterization of ADC samples (Jul – Aug)
 - optimization of ADC design or ADC IP (S3) and migration to IBM 130nm
 - design of 16-channel of complete readout chain (with simplified digital processor)
- 2010
 - characterization of 16-channel prototype
 - decide how to continue the project according to the results achieved

Advanced Endplate: S-ALTRO

Design of Pad Board



LAYER STACKUP

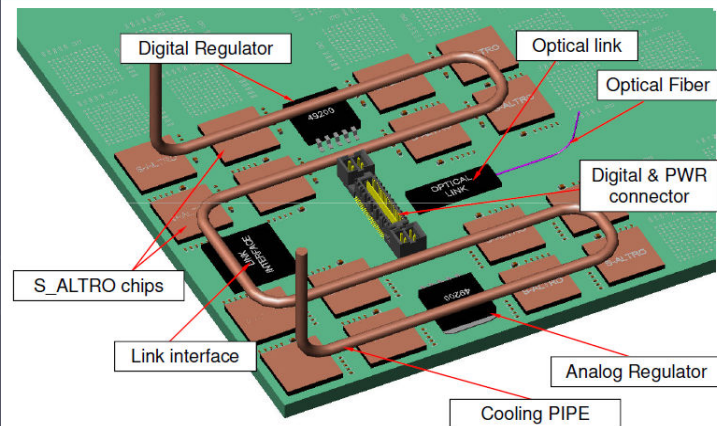


Antoine JUNIQUE

3

18 layer PAD PCB

MODULE DETAILS



Antoine JUNIQUE

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Option of Cooling: 2-phase CO₂ cooling/traditional H₂O cooling

Advanced Endplate: PCB Test Test with a Pad PCB model

Test:

Power switching

Power delivery

Cooling:

Thermo-mechanical test

In a high field (DESY 5T magnet, PCMAG, etc.)

Pad PCB model:

Realistic design of pad PCB with all components
64ch S-ALTROs replaced by proper FPGAs and
OP amp/ADC as current load and heat source.

Connect pads to the FPGA analog outputs

Try cooling by the 2-phase CO2 cooling

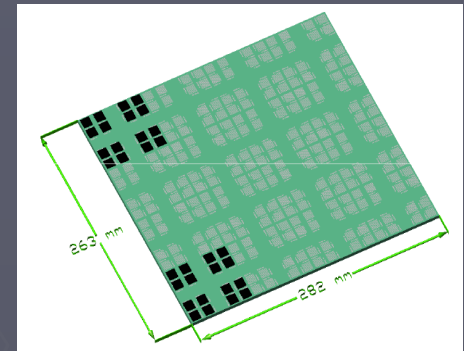
(AMS and LHCb: Bart Verlaet/Nikhef)

Test also digital software model/communication in FPGA

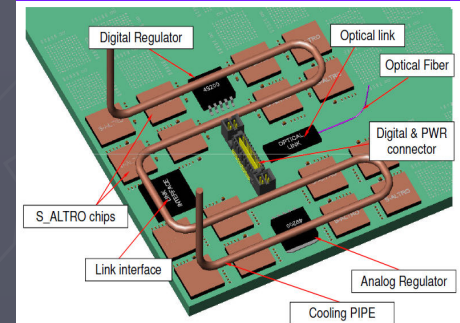
Test in high magnetic field

Schedule: 2010

S-ALTRO Team
LC TPC groups



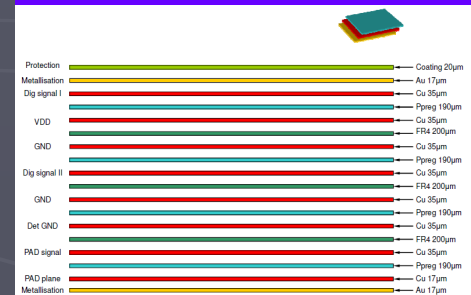
MODULE DETAILS



Antoine JUNIQUE

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LAYER STACKUP



Antoine JUNIQUE

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Advanced Endplate: Cooling Option of the 2-phase CO₂ cooling

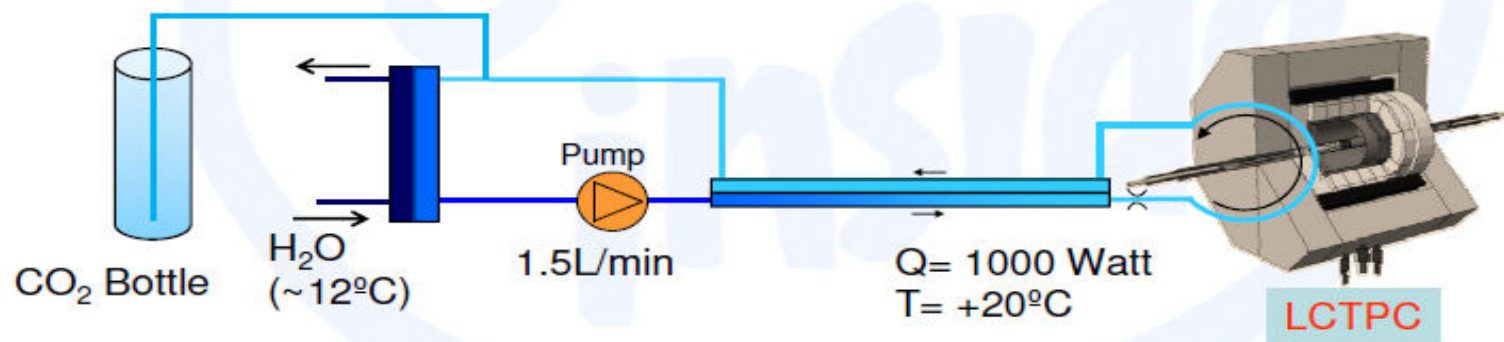


2PACL for LCTPC

Warm 2PACL very simple

- Accumulator is CO₂ bottle @ room temperature
- Cold source is cold water

Bottle temperature = Detector temperature



AMS-TTCS was tested in the same way
(Cold test done with bottle outside in winter)

Advanced Endplate: Cooling

Preliminary Design Consideration for ILC TPC

Advantage of thin piping (high pressure)



TPC end plate cooling tube routing

Possible layout of the 6 loops option

Liquid supply ring (~5mm ID)

Vapor return ring (~8mm ID)

Cooling tube (~2.5mm ID)

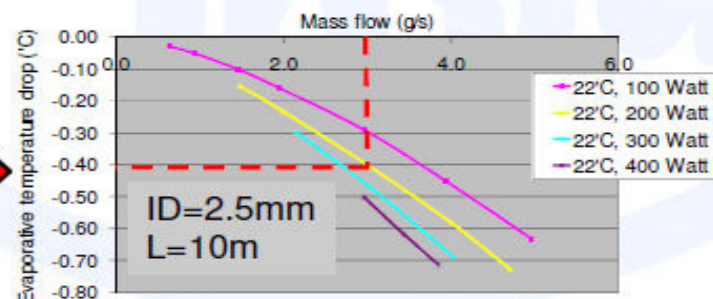
Inlet capillary (~1mm ID)

Restriction for flow distribution

	Qty Frames / loop	Heat load per loop (W)	Tube length (m)	Inner diameter (mm)
1 loop	200	1000	48m	6.2
2 loops	100	500	24m	4.3
4 loops	50	250	12m	3
6 loops	34	171	8m	2.2

Similar to AMS-TTCS

AMS test data (2001)
0.4°C temperature gradient



Conclusions

MPGD TPC options at ILC (ILD) TPC provide a large number of space points (200) with the excellent point resolution down to 100microns over 2m drift distance. It is a truly-visual 3D tracker works in high magnetic field providing the performance necessary for the experimentation at ILC.

The TPC Large Prototype test at DESY (LP1) by LC TPC collaboration using the EUDET facility is being carried out successfully since November 2008.

We look forward to performing momentum measurement in non uniform magnetic field of PCMAG with full length tracks in the multi modules setup in 2010.

From 2011 we plan to perform beam tests with a high energy hadron beam.

There are important engineering issues to realize MPGD TPC for ILC (ILD): R&D for the advanced endplate and R&Ds for ion feed back/gating devices.